

Application No. 10/099,870

Filed: March 14, 2002

TC Art Unit: 2825

Confirmation No.: 4461

AMENDMENTS TO THE SPECIFICATION

Please amend the specification by adding the following appropriate headings:

On page 1, line 1, before the paragraph beginning with "This invention relates to..." please add the heading FIELD OF THE INVENTION.

On page 1, before the paragraph beginning with "During the performance of a process treatment..." please add the heading BACKGROUND OF THE INVENTION.

On page 2, before the paragraph beginning with "The object of the present invention..." at line 20, please add the following heading SUMMARY OF THE INVENTION.

On page 7, before the paragraph beginning with "Further elaborations of the invention..." please add the following heading BRIEF DESCRIPTION OF THE FIGURES. Also, please move the entire section of text regarding the figures from line 3 to line 17, including the new corresponding heading, to page 4, before the paragraph beginning with "In a process device..."

On page 4, before the paragraph beginning with "In a process device..." and after the moved text regarding the figures, please add the following heading DETAILED DESCRIPTION OF THE INVENTION.

Please amend the specification on page 8, lines 1-15, as follows:

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Fig. 3 shows a side elevation of a substrate 20 having thereon the camera capsule 21 mentioned earlier. As a substrate 20, a 300 mm silicon wafer has been taken, and the camera having a diameter of 11 mm and a length of 30 mm is indicated on scale thereon. Fig. 4 shows a top plan view of a wafer having arranged thereon a camera capsule. Depending on the situation in which the sensor wafer is used and the need for inspection, several cameras can be arranged on the wafer, as shown in Fig. 5. Optionally, two cameras arranged parallel and substantially at eye distance can be used, so that a stereo image can be created. In addition, it is possible for the cameras to be arranged displaceably on the wafers, with the aid of any technique known for that purpose, such as clamping, adhesion, magnets, and the like. Depending on the space in the process device and the transport mechanism for the substrate, the camera can also be attached to the undersurface of the wafer. Finally, it is also possible to provide a recess in the support and to have the camera project partly above the wafer and partly under the wafer.